

Technical Data Sheet

Product Code: 0005321 Revised Date: 10/24/2024

Dissolvene MS-40

Product Description

Dissolvene MS-40 is an aqueous based alkaline solution designed to strip and remove a cured dry film solder mask as well as most liquid solder masks from printed circuit boards.

Performance Features

- Dissolvene MS-40 will not attack bottom coat of base laminate
- Dissolvene MS-40 will effectively remove all cured dry film and liquid photo-imageable solder mask in about 10-40 minutes

Physical Specifications

Physical State	Liquid
Appearance	Water White
рН	>12
Water Solubility	Complete

Equipment Requirements

Tanks should be constructed of stainless steel or reinforced, heat-resistant polypropylene. Racks should be stainless steel and the heaters should be constructed of stainless steel.

Product Make-Up

Dissolvene MS-40 is a ready to use product and should NOT be diluted.

Concentration and Application Method

The performance of Dissolvene MS-40 increases with elevated temperature.

Temperature	140 °F to 160 °F
Circulation Time	10 to 45 minutes

Procedure

- 1. Pipette a 2mL sample of Dissolvene MS-40 working bath into a 250mL Erlenmeyer Flask
- Add 50mL of Deionized Water.
- Add 5 to 10 drops of Phenolphthalein Indicator.
- 4. Titrate with 1.0N Hydrochloric Acid, with stirring or swirling of flask, to a water clear endpoint.

% Dissolvene MS-40 = mL of HCL X Normality of HCI X 8

Maintenance

Dissolvene MS-40 should be maintained between 80% and 100% for optimum results.

Safety and Handling

Please review and understand the Dissolvene MS-40 SDS before handling.

Waste Treatment

Individual users should verify the nature of spent solutions to assure compliance with local, state, and federal regulations.



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Ordering Information

Dissolvene MS-40 is available in 5-gallon pails and 55-gallon drums.





